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(54) **ELECTRONIC DEVICE AND
MANUFACTURING METHOD FOR MIDDLE
FRAME**

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(57) **ABSTRACT**

An electronic device and a manufacturing method for a middle frame are provided. The electronic device includes a middle frame, and the middle frame includes a bezel and a middle plate. The bezel is of an annular structure and is disposed around an edge of the middle plate, and the bezel includes at least two layers of annular structures. A concavo-convex fit between any two adjacent annular structures in the at least two layers of annular structures is used to locate the annular structure. The at least two layers of annular structures are respectively at least two metal materials of different densities. In this application, in a processing manner of hot forging a composite plate, the bezel, the middle plate, and a rib in the middle frame are an integrated structure, and at least two types of metal are arranged on the bezel at the same time.

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